semi

DATE 08 JAN 2019

X2DFN3 1.0x0.6, 0.35P CASE 714AC **ISSUE A** SCALE 8:1 Α PIN DNE В D REFERENCE 0.10 C Е 0.10 C TOP VIEW NDTE 3 Α // 0.10 C 3X 0.10 C A1 SEATING С SIDE VIEW PLANE e1 - b1 e/2 e 3X L 2X b 0.10 M C A B Φ 0.05 M C BOTTOM VIEW NDTE 4 GENERIC **MARKING DIAGRAM*** 0 XX M

> *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

XX = Specific Device Code

M = Date Code

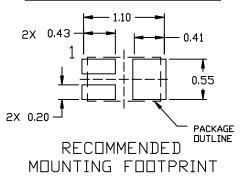
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DESCRIPTION:	X2DFN3 1.0x0.6, 0.35P		PAGE 1 OF 1

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NDTES:

- DIMENSIONING AND TOLERANCING PER 1. ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. EXPOSED COPPER ALLOWED AS SHOWN.
- ALL PAD LOCATIONS CONTROLLED WITH 4. THIS POSITIONAL TOLERANCE.

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A	0.34	0.37	0.40	
A1	0.00		0.05	
b	0.10	0.15	0.20	
b1	0.45	0.50	0.55	
D	0.95	1.00	1.05	
E	0.55	0.60	0.65	
e	0.35 BSC			
e1	0.65 BSC			
L	0.20	0.25	0.30	



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